LMT87 2.7-V, SC70/TO-92/TO-92S,
Analog Temperature Sensors With Class-AB Output

1 Features
• LMT87LPG (TO-92S package) has a Fast Thermal Time Constant, 10-s Typical (1.2 m/s Airflow)
• Very Accurate: ±0.4°C Typical
• Low 2.7-V Operation
• Average Sensor Gain of -13.6 mV/°C
• Low 5.4-µA Quiescent Current
• Wide Temperature Range: –50°C to 150°C
• Output is Short-Circuit Protected
• Push-Pull Output With ±50-µA Drive Capability
• Footprint Compatible With the Industry-Standard LM20/19 and LM35 Temperature Sensors
• Cost-Effective Alternative to Thermistors

2 Applications
• Automotive
• Infotainment and Cluster
• Powertrain Systems
• Smoke and Heat Detectors
• Drones
• Appliances

3 Description
The LMT87 device is a precision CMOS temperature sensor with ±0.4°C typical accuracy (±2.7°C maximum) and a linear analog output voltage that is inversely proportional to temperature. The 2.7-V supply voltage operation, 5.4-µA quiescent current, and 0.7-ms power-on time enable effective power-cycling architectures to minimize power consumption for battery-powered applications such as drones and sensor nodes. The LMT87LPG through-hole TO-92S package fast thermal time constant supports off-board time-temperature sensitive applications such as smoke and heat detectors. The accuracy over the wide operating range and other features make the LMT87 an excellent alternative to thermistors.

For devices with different average sensor gains and comparable accuracy, refer to Comparable Alternative Devices for alternative devices in the LMT8x family.

Device Information(1)

<table>
<thead>
<tr>
<th>PART NUMBER</th>
<th>PACKAGE</th>
<th>BODY SIZE (NOM)</th>
</tr>
</thead>
<tbody>
<tr>
<td>LMT87</td>
<td>SOT (5)</td>
<td>2.00 mm × 1.25 mm</td>
</tr>
<tr>
<td></td>
<td>TO-92 (3)</td>
<td>4.30 mm × 3.50 mm</td>
</tr>
<tr>
<td></td>
<td>TO-92S (3)</td>
<td>4.00 mm × 3.15 mm</td>
</tr>
</tbody>
</table>

(1) For all available packages, see the orderable addendum addendum at the end of the data sheet.

Thermal Time Constant

Output Voltage vs Temperature

* Fast thermal response NTC
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4 Revision History
NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Revision D (June 2017) to Revision E

• Moved the automotive device to a standalone data sheet (SNIS202) ......................................................... 1
• Changed TO-92 GND pin number from: 1 to: 3 ................................................................. 4
• Changed TO-92 VDD pin number from: 3 to: 1 .............................................................. 4

Changes from Revision C (October 2015) to Revision D

• Updated data sheet text to the latest documentation and translations standards ........................................ 1
• Added AEC-Q100 automotive qualification bullets to Features ......................................................... 1
• Added Time Constant graph .......................................................... 1
• Removed disk drivers, games, wireless transceivers, and cell phones from Applications .......................... 1
• Added LPG (TO-92S) package ................................................................................. 4
• Added Figure 10 to Typical Characteristics ............................................................................. 7

Changes from Revision B (May 2014) to Revision C

• Deleted all mentions of TO-126 package ................................................................. 1
• Added TO-92 LPM pin configuration graphic ........................................................................... 4
• Changed Handling Ratings to ESD Ratings and moved Storage Temperature to Absolute Maximum Ratings table ............................................................. 5
• Changed KV to V .......................................................... 5
• Added layout recommendation for TO-92 LP and LPM packages ............................................ 15

Changes from Revision A (June 2013) to Revision B

• Added data sheet flow and layout to conform with new TI standards. Added the following sections: Application and Implementation, Power Supply Recommendations, Layout, Device and Documentation Support, Mechanical, Packaging, and Orderable Information ................................................................. 1
• Added TO-92 and TO-126 package information ........................................................................... 1
5 Device Comparison Tables

Table 1. Available Device Packages

<table>
<thead>
<tr>
<th>ORDER NUMBER(1)</th>
<th>PACKAGE</th>
<th>PIN</th>
<th>BODY SIZE (NOM)</th>
<th>MOUNTING TYPE</th>
</tr>
</thead>
<tbody>
<tr>
<td>LMT87DCK</td>
<td>SOT (AKA(2); SC70, DCK)</td>
<td>5</td>
<td>2.00 mm × 1.25 mm</td>
<td>Surface Mount</td>
</tr>
<tr>
<td>LMT87LP</td>
<td>TO-92 (AKA(2); LP)</td>
<td>3</td>
<td>4.30 mm × 3.50 mm</td>
<td>Through-hole; straight leads</td>
</tr>
<tr>
<td>LMT87LPG</td>
<td>TO-92S (AKA(2); LPG)</td>
<td>3</td>
<td>4.00 mm × 3.15 mm</td>
<td>Through-hole; straight leads</td>
</tr>
<tr>
<td>LMT87LPM</td>
<td>TO-92 (AKA(2); LPM)</td>
<td>3</td>
<td>4.30 mm × 3.50 mm</td>
<td>Through-hole; formed leads</td>
</tr>
<tr>
<td>LMT87DCK-Q1</td>
<td>SOT (AKA(2); SC70, DCK)</td>
<td>5</td>
<td>2.00 mm × 1.25 mm</td>
<td>Surface Mount</td>
</tr>
</tbody>
</table>

(1) For all available packages and complete order numbers, see the Package Option addendum at the end of the data sheet.
(2) AKA = Also Known As

Table 2. Comparable Alternative Devices

<table>
<thead>
<tr>
<th>DEVICE NAME</th>
<th>AVERAGE OUTPUT SENSOR GAIN</th>
<th>POWER SUPPLY RANGE</th>
</tr>
</thead>
<tbody>
<tr>
<td>LMT84</td>
<td>−5.5 mV/°C</td>
<td>1.5 V to 5.5 V</td>
</tr>
<tr>
<td>LMT85</td>
<td>−8.2 mV/°C</td>
<td>1.8 V to 5.5 V</td>
</tr>
<tr>
<td>LMT86</td>
<td>−10.9 mV/°C</td>
<td>2.2 V to 5.5 V</td>
</tr>
<tr>
<td>LMT87</td>
<td>−13.6 mV/°C</td>
<td>2.7 V to 5.5 V</td>
</tr>
</tbody>
</table>
## 6 Pin Configuration and Functions

### Pin Functions

<table>
<thead>
<tr>
<th>PIN</th>
<th>TYPE</th>
<th>DESCRIPTION</th>
</tr>
</thead>
<tbody>
<tr>
<td>GND</td>
<td>Ground</td>
<td>Power Supply Ground</td>
</tr>
<tr>
<td>OUT</td>
<td>Analog Output</td>
<td>Outputs a voltage that is inversely proportional to temperature</td>
</tr>
<tr>
<td>VDD</td>
<td>Power</td>
<td>Positive Supply Voltage</td>
</tr>
</tbody>
</table>

(1) Direct connection to the back side of the die
7 Specifications

7.1 Absolute Maximum Ratings

<table>
<thead>
<tr>
<th>Parameter</th>
<th>MIN</th>
<th>MAX</th>
<th>UNIT</th>
</tr>
</thead>
<tbody>
<tr>
<td>Supply voltage</td>
<td>–0.3</td>
<td>6</td>
<td>V</td>
</tr>
<tr>
<td>Voltage at output pin</td>
<td>–0.3</td>
<td>(V_{DD} + 0.5)</td>
<td>V</td>
</tr>
<tr>
<td>Output current</td>
<td>–7</td>
<td>7</td>
<td>mA</td>
</tr>
<tr>
<td>Input current at any pin (3)</td>
<td>–5</td>
<td>5</td>
<td>mA</td>
</tr>
<tr>
<td>Maximum junction temperature (T_{JMAX})</td>
<td></td>
<td>150</td>
<td>°C</td>
</tr>
<tr>
<td>Storage temperature T_{stg}</td>
<td>–65</td>
<td>150</td>
<td>°C</td>
</tr>
</tbody>
</table>

(1) Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under Recommended Operating Conditions. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) Soldering process must comply with Reflow Temperature Profile specifications. Refer to www.ti.com/packaging.

(3) When the input voltage (V_{i}) at any pin exceeds power supplies (V_{i} < GND or V_{i} > V), the current at that pin should be limited to 5 mA.

7.2 ESD Ratings

<table>
<thead>
<tr>
<th>Device</th>
<th>VALUE</th>
<th>UNIT</th>
</tr>
</thead>
<tbody>
<tr>
<td>LMT87LP in TO-92 package</td>
<td></td>
<td></td>
</tr>
<tr>
<td>V_{(ESD)} Electrostatic discharge Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001(1)(2)</td>
<td>±2500</td>
<td>V</td>
</tr>
<tr>
<td></td>
<td>Charged-device model (CDM), per JEDEC specification JESD22-C101(3)</td>
<td>±1000</td>
</tr>
<tr>
<td>LMT87DCK in SC70 package</td>
<td></td>
<td></td>
</tr>
<tr>
<td>V_{(ESD)} Electrostatic discharge Human-body model (HBM), per JESD22-A114(2)</td>
<td>±2500</td>
<td>V</td>
</tr>
<tr>
<td></td>
<td>Charged-device model (CDM), per JEDEC specification JESD22-C101(3)</td>
<td>±1000</td>
</tr>
</tbody>
</table>

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.

(2) The human-body model is a 100-pF capacitor discharged through a 1.5-kΩ resistor into each pin.

(3) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

7.3 Recommended Operating Conditions

<table>
<thead>
<tr>
<th>Parameter</th>
<th>MIN</th>
<th>MAX</th>
<th>UNIT</th>
</tr>
</thead>
<tbody>
<tr>
<td>Specified temperature</td>
<td>T_{MIN} ≤ T_{A} ≤ T_{MAX}</td>
<td>°C</td>
<td></td>
</tr>
<tr>
<td>Supply voltage (V_{DD})</td>
<td>–50 ≤ T_{A} ≤ 150</td>
<td>°C</td>
<td></td>
</tr>
<tr>
<td></td>
<td>2.7</td>
<td>5.5</td>
<td>V</td>
</tr>
</tbody>
</table>

7.4 Thermal Information

<table>
<thead>
<tr>
<th>THERMAL METRIC(2)</th>
<th>LMT87</th>
<th>LMT87LP</th>
<th>LMT87/LPG</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td>DCK (SOT/SC70)</td>
<td>LP/LPM (TO-92)</td>
<td>LPG (TO-92S)</td>
</tr>
<tr>
<td></td>
<td>5 PINS</td>
<td>3 PINS</td>
<td>3 PINS</td>
</tr>
<tr>
<td>R_{UA} Junction-to-ambient thermal resistance (3)(4)</td>
<td>275</td>
<td>167</td>
<td>130.4</td>
</tr>
<tr>
<td>R_{UC(top)} Junction-to-case (top) thermal resistance</td>
<td>84</td>
<td>90</td>
<td>64.2</td>
</tr>
<tr>
<td>R_{UB} Junction-to-board thermal resistance</td>
<td>56</td>
<td>146</td>
<td>106.2</td>
</tr>
<tr>
<td>V_{JT} Junction-to-top characterization parameter</td>
<td>1.2</td>
<td>35</td>
<td>14.6</td>
</tr>
<tr>
<td>V_{JB} Junction-to-board characterization parameter</td>
<td>55</td>
<td>146</td>
<td>106.2</td>
</tr>
</tbody>
</table>

(1) For information on self-heating and thermal response time see section Mounting and Thermal Conductivity.

(2) For more information about traditional and new thermal metrics, see the IC Package Thermal Metrics application report.

(3) The junction to ambient thermal resistance (R_{UA}) under natural convection is obtained in a simulation on a JEDEC-standard, High-K board as specified in JESD51-7, in an environment described in JESD51-2. Exposed pad packages assume that thermal vias are included in the PCB, per JESD 51-5.

(4) Changes in output due to self-heating can be computed by multiplying the internal dissipation by the thermal resistance.
### 7.5 Accuracy Characteristics

These limits do not include DC load regulation. These stated accuracy limits are with reference to the values in Table 3.

<table>
<thead>
<tr>
<th>PARAMETER</th>
<th>CONDITIONS</th>
<th>MIN(1)</th>
<th>TYP</th>
<th>MAX(1)</th>
<th>UNIT</th>
</tr>
</thead>
<tbody>
<tr>
<td>Temperature accuracy(2)</td>
<td>70°C to 150°C; $V_{DD} = 3.0$ V to 5.5 V</td>
<td>−2.7</td>
<td>±0.4</td>
<td>2.7</td>
<td>°C</td>
</tr>
<tr>
<td></td>
<td>20°C to 40°C; $V_{DD} = 2.7$ V to 5.5 V</td>
<td>±0.6</td>
<td></td>
<td></td>
<td>°C</td>
</tr>
<tr>
<td></td>
<td>20°C to 40°C; $V_{DD} = 3.4$ V to 5.5 V</td>
<td>±0.3</td>
<td></td>
<td></td>
<td>°C</td>
</tr>
<tr>
<td></td>
<td>0°C; $V_{DD} = 3.0$ V to 5.5 V</td>
<td>−2.7</td>
<td>±0.6</td>
<td>2.7</td>
<td>°C</td>
</tr>
<tr>
<td></td>
<td>0°C; $V_{DD} = 3.6$ V to 5.5 V</td>
<td>±0.3</td>
<td></td>
<td></td>
<td>°C</td>
</tr>
<tr>
<td></td>
<td>−50°C; $V_{DD} = 3.6$ V to 5.5 V</td>
<td>−2.7</td>
<td>±0.6</td>
<td>2.7</td>
<td>°C</td>
</tr>
<tr>
<td></td>
<td>−50°C; $V_{DD} = 4.2$ V to 5.5 V</td>
<td>±0.3</td>
<td></td>
<td></td>
<td>°C</td>
</tr>
</tbody>
</table>

(1) Limits are specific to TI's AOQL (Average Outgoing Quality Level).
(2) Accuracy is defined as the error between the measured and reference output voltages, tabulated in the Transfer Table at the specified conditions of supply gain setting, voltage, and temperature (expressed in °C). Accuracy limits include line regulation within the specified conditions. Accuracy limits do not include load regulation; they assume no DC load.

### 7.6 Electrical Characteristics

Unless otherwise noted, these specifications apply for $+V_{DD} = 2.7$ V to 5.5 V. MIN and MAX limits apply for $T_A = T_J = T_{MIN}$ to $T_{MAX}$: typical limits apply for $T_A = T_J = 25°C$.

<table>
<thead>
<tr>
<th>PARAMETER</th>
<th>TEST CONDITIONS</th>
<th>MIN(1)</th>
<th>TYP (2)</th>
<th>MAX (1)</th>
<th>UNIT</th>
</tr>
</thead>
<tbody>
<tr>
<td>Sensor gain (output transfer</td>
<td>Source ≤ 50 µA, $(V_{DD} - V_{OUT}) ≥ 200$ mV</td>
<td>−12.6</td>
<td></td>
<td></td>
<td>mV/°C</td>
</tr>
<tr>
<td>function slope</td>
<td>Sink ≤ 50 µA, $V_{OUT} ≥ 200$ mV</td>
<td>−0.22</td>
<td></td>
<td></td>
<td>mV</td>
</tr>
<tr>
<td>Load regulation(3)</td>
<td></td>
<td>−1</td>
<td>0.26</td>
<td>1</td>
<td>mV/V</td>
</tr>
<tr>
<td>Line regulation(4)</td>
<td></td>
<td>200</td>
<td></td>
<td></td>
<td>µV/V</td>
</tr>
<tr>
<td>$I_S$</td>
<td>$T_A = 30°C$ to 150°C, $(V_{DD} - V_{OUT}) ≥ 100$ mV</td>
<td>5.4</td>
<td>8.1</td>
<td></td>
<td>µA</td>
</tr>
<tr>
<td></td>
<td>$T_A = −50°C$ to 150°C, $(V_{DD} - V_{OUT}) ≥ 100$ mV</td>
<td>5.4</td>
<td>9</td>
<td></td>
<td>µA</td>
</tr>
<tr>
<td>Output load capacitance</td>
<td>$C_L = 0$ pF to 1100 pF</td>
<td>0.7</td>
<td>1.9</td>
<td></td>
<td>pF</td>
</tr>
<tr>
<td>Output drive</td>
<td>$T_A = T_J = 25°C$</td>
<td>−50</td>
<td>50</td>
<td></td>
<td>µA</td>
</tr>
</tbody>
</table>

(1) Limits are specific to TI's AOQL (Average Outgoing Quality Level).
(2) Typicals are at $T_J = T_A = 25°C$ and represent most likely parametric norm.
(3) Source currents are flowing out of the LMT87. Sink currents are flowing into the LMT87.
(4) Line regulation (DC) is calculated by subtracting the output voltage at the highest supply voltage from the output voltage at the lowest supply voltage. The typical DC line regulation specification does not include the output voltage shift discussed in Output Voltage Shift.
(5) Specified by design and characterization.
7.7 Typical Characteristics

Figure 1. Temperature Error vs Temperature

Figure 2. Minimum Operating Temperature vs Supply Voltage

Figure 3. Supply Current vs Temperature

Figure 4. Supply Current vs Supply Voltage

Figure 5. Load Regulation, Sourcing Current

Figure 6. Load Regulation, Sinking Current
Typical Characteristics (continued)

![Figure 7. Change in V\text{OUT} vs Overhead Voltage](image1)

![Figure 8. Supply-Noise Gain vs Frequency](image2)

![Figure 9. Output Voltage vs Supply Voltage](image3)

![Figure 10. LMT87LPG Thermal Response vs Common Leaded Thermistor With 1.2-m/s Airflow](image4)
8 Detailed Description

8.1 Overview

The LMT87 is an analog output temperature sensor. The temperature-sensing element is comprised of a simple base emitter junction that is forward biased by a current source. The temperature-sensing element is then buffered by an amplifier and provided to the OUT pin. The amplifier has a simple push-pull output stage thus providing a low impedance output source.

8.2 Functional Block Diagram

Full-Range Celsius Temperature Sensor (−50°C to +150°C)

8.3 Feature Description

8.3.1 LMT87 Transfer Function

The output voltage of the LMT87, across the complete operating temperature range, is shown in Table 3. This table is the reference from which the LMT87 accuracy specifications (listed in the Accuracy Characteristics section) are determined. This table can be used, for example, in a host processor look-up table. A file containing this data is available for download at the LMT87 product folder under Tools and Software Models.

<table>
<thead>
<tr>
<th>TEMP (°C)</th>
<th>V_OUT (mV)</th>
<th>TEMP (°C)</th>
<th>V_OUT (mV)</th>
<th>TEMP (°C)</th>
<th>V_OUT (mV)</th>
<th>TEMP (°C)</th>
<th>V_OUT (mV)</th>
<th>TEMP (°C)</th>
<th>V_OUT (mV)</th>
</tr>
</thead>
<tbody>
<tr>
<td>−50</td>
<td>3277</td>
<td>−10</td>
<td>2767</td>
<td>30</td>
<td>2231</td>
<td>70</td>
<td>1679</td>
<td>110</td>
<td>1115</td>
</tr>
<tr>
<td>−49</td>
<td>3266</td>
<td>−9</td>
<td>2754</td>
<td>31</td>
<td>2217</td>
<td>71</td>
<td>1665</td>
<td>111</td>
<td>1101</td>
</tr>
<tr>
<td>−48</td>
<td>3254</td>
<td>−8</td>
<td>2740</td>
<td>32</td>
<td>2204</td>
<td>72</td>
<td>1651</td>
<td>112</td>
<td>1087</td>
</tr>
<tr>
<td>−47</td>
<td>3243</td>
<td>−7</td>
<td>2727</td>
<td>33</td>
<td>2190</td>
<td>73</td>
<td>1637</td>
<td>113</td>
<td>1073</td>
</tr>
<tr>
<td>−46</td>
<td>3232</td>
<td>−6</td>
<td>2714</td>
<td>34</td>
<td>2176</td>
<td>74</td>
<td>1623</td>
<td>114</td>
<td>1058</td>
</tr>
<tr>
<td>−45</td>
<td>3221</td>
<td>−5</td>
<td>2700</td>
<td>35</td>
<td>2163</td>
<td>75</td>
<td>1609</td>
<td>115</td>
<td>1044</td>
</tr>
<tr>
<td>−44</td>
<td>3210</td>
<td>−4</td>
<td>2687</td>
<td>36</td>
<td>2149</td>
<td>76</td>
<td>1595</td>
<td>116</td>
<td>1030</td>
</tr>
<tr>
<td>−43</td>
<td>3199</td>
<td>−3</td>
<td>2674</td>
<td>37</td>
<td>2136</td>
<td>77</td>
<td>1581</td>
<td>117</td>
<td>1015</td>
</tr>
<tr>
<td>−42</td>
<td>3186</td>
<td>−2</td>
<td>2660</td>
<td>38</td>
<td>2122</td>
<td>78</td>
<td>1567</td>
<td>118</td>
<td>1001</td>
</tr>
<tr>
<td>−41</td>
<td>3173</td>
<td>−1</td>
<td>2647</td>
<td>39</td>
<td>2108</td>
<td>79</td>
<td>1553</td>
<td>119</td>
<td>987</td>
</tr>
<tr>
<td>−40</td>
<td>3160</td>
<td>0</td>
<td>2633</td>
<td>40</td>
<td>2095</td>
<td>80</td>
<td>1539</td>
<td>120</td>
<td>973</td>
</tr>
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<td>2067</td>
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<td>1511</td>
<td>122</td>
<td>944</td>
</tr>
</tbody>
</table>

Table 3. LMT87 Transfer Table
Although the LMT87 is very linear, the response does have a slight umbrella parabolic shape. This shape is very accurately reflected in Table 3. The transfer table can be calculated by using the parabolic equation (Equation 1).

\[ V_{\text{TEMP}} \ (\text{mV}) = 2230.8 \text{mV} - \left[ \frac{13.582 \text{mV}}{\degree \text{C}} (T - 30 \degree \text{C}) \right] - \left[ \frac{0.00433 \text{mV}}{\degree \text{C}^2} (T - 30 \degree \text{C})^2 \right] \]  

(1)

The parabolic equation is an approximation of the transfer table and the accuracy of the equation degrades slightly at the temperature range extremes. **Equation 1** can be solved for T resulting in:

\[ T = \frac{13.582 - \sqrt{(-13.582)^2 + 4 \times 0.00433 \times (2230.8 - V_{\text{TEMP}} \ (\text{mV}))}}{2 \times (-0.00433)} + 30 \]  

(2)

For an even less accurate linear transfer function approximation, a line can easily be calculated over the desired temperature range from **Table 3** using the two-point equation (Equation 3):

\[ V - V_1 = \left( \frac{V_2 - V_1}{T_2 - T_1} \right) \times (T - T_1) \]

where

- \( V \) is in mV,
- \( T \) is in °C,
- \( T_1 \) and \( V_1 \) are the coordinates of the lowest temperature,
- \( T_2 \) and \( V_2 \) are the coordinates of the highest temperature.

(3)
For example, if the user wanted to resolve this equation, over a temperature range of 20°C to 50°C, they would proceed as follows:

\[
V = 2365 \text{ mV} = \left( \frac{1958 \text{ mV} - 2365 \text{ mV}}{50^\circ \text{C} - 20^\circ \text{C}} \right) \times (T - 20^\circ \text{C}) \\
V = 2365 \text{ mV} = (-13.6 \text{ mV/}^\circ \text{C}) \times (T - 20^\circ \text{C}) \\
V = (-13.6 \text{ mV/}^\circ \text{C}) \times T + 2637 \text{ mV}
\]

Using this method of linear approximation, the transfer function can be approximated for one or more temperature ranges of interest.

### 8.4 Device Functional Modes

#### 8.4.1 Mounting and Thermal Conductivity

The LMT87 can be applied easily in the same way as other integrated-circuit temperature sensors. It can be glued or cemented to a surface.

To ensure good thermal conductivity, the backside of the LMT87 die is directly attached to the GND pin. The temperatures of the lands and traces to the other leads of the LMT87 will also affect the temperature reading.

Alternatively, the LMT87 can be mounted inside a sealed-end metal tube, and can then be dipped into a bath or screwed into a threaded hole in a tank. As with any IC, the LMT87 and accompanying wiring and circuits must be kept insulated and dry, to avoid leakage and corrosion. This is especially true if the circuit may operate at cold temperatures where condensation can occur. If moisture creates a short circuit from the output to ground or V\(_{DD}\), the output from the LMT87 will not be correct. Printed-circuit coatings are often used to ensure that moisture cannot corrode the leads or circuit traces.

The thermal resistance junction to ambient (R\(_{JA}\) or θ\(_{JA}\)) is the parameter used to calculate the rise of a device junction temperature due to its power dissipation. Use Equation 7 to calculate the rise in the LMT87 die temperature:

\[
T_J = T_A + \theta_{JA} \left[ I_{SD} \right] + \left( V_{DD} \cdot V_{OUT} \right) I_L
\]

where

- \( T_A \) is the ambient temperature,
- \( I_S \) is the supply current,
- \( I_L \) is the load current on the output,
- and \( V_O \) is the output voltage.

For example, in an application where \( T_A = 30^\circ \text{C}, V_{DD} = 5 \text{ V}, I_S = 5.4 \mu\text{A}, V_{OUT} = 2231 \text{ mV}, \) and \( I_L = 2 \mu\text{A}, \) the junction temperature would be 30.014°C, showing a self-heating error of only 0.014°C. Because the junction temperature of the LMT87 is the actual temperature being measured, take care to minimize the load current that the LMT87 is required to drive. *Thermal Information*\(^{(1)}\) shows the thermal resistance of the LMT87.

#### 8.4.2 Output Noise Considerations

A push-pull output gives the LMT87 the ability to sink and source significant current. This is beneficial when, for example, driving dynamic loads like an input stage on an analog-to-digital converter (ADC). In these applications the source current is required to quickly charge the input capacitor of the ADC. The LMT87 is ideal for this and other applications which require strong source or sink current.

The LMT87 supply-noise gain (the ratio of the AC signal on V\(_{OUT}\) to the AC signal on V\(_{DD}\)) was measured during bench tests. The typical attenuation is shown in Figure 8 found in the *Typical Characteristics* section. A load capacitor on the output can help to filter noise.

For operation in very noisy environments, some bypass capacitance should be present on the supply within approximately 5 centimeters of the LMT87.

---

\(^{(1)}\) For information on self-heating and thermal response time see section *Mounting and Thermal Conductivity.*
Device Functional Modes (continued)

8.4.3 Capacitive Loads

The LMT87 handles capacitive loading well. In an extremely noisy environment, or when driving a switched sampling input on an ADC, it may be necessary to add some filtering to minimize noise coupling. Without any precautions, the LMT87 can drive a capacitive load less than or equal to 1100 pF, as shown in Figure 11. For capacitive loads greater than 1100 pF, a series resistor may be required on the output, as shown in Figure 12.

![Figure 11. LMT87 No Decoupling Required for Capacitive Loads Less Than 1100 pF](image1)

![Figure 12. LMT87 with Series Resistor for Capacitive Loading Greater Than 1100 pF](image2)

Table 4. Recommended Series Resistor Values

<table>
<thead>
<tr>
<th>C_{LOAD}</th>
<th>MINIMUM R_S</th>
</tr>
</thead>
<tbody>
<tr>
<td>1.1 nF to 99 nF</td>
<td>3 kΩ</td>
</tr>
<tr>
<td>100 nF to 999 nF</td>
<td>1.5 kΩ</td>
</tr>
<tr>
<td>1 μF</td>
<td>800 Ω</td>
</tr>
</tbody>
</table>

8.4.4 Output Voltage Shift

The LMT87 is very linear over temperature and supply voltage range. Due to the intrinsic behavior of an NMOS/PMOS rail-to-rail buffer, a slight shift in the output can occur when the supply voltage is ramped over the operating range of the device. The location of the shift is determined by the relative levels of V_{DD} and V_{OUT}. The shift typically occurs when V_{DD} - V_{OUT} = 1 V.

This slight shift (a few millivolts) takes place over a wide change (approximately 200 mV) in V_{DD} or V_{OUT}. Because the shift takes place over a wide temperature change of 5°C to 20°C, V_{OUT} is always monotonic. The accuracy specifications in the *Accuracy Characteristics* table already include this possible shift.
## 9 Application and Implementation

**NOTE**

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI’s customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

### 9.1 Application Information

The LMT87 features make it suitable for many general temperature-sensing applications. It can operate down to 2.7-V supply with 5.4-µA power consumption. Package options like the through-hole TO-92 package also allow the LMT87 to be mounted onboard, off-board, to a heat sink, or on multiple unique locations in the same application.

### 9.2 Typical Applications

#### 9.2.1 Connection to ADC

#### 9.2.1.1 Design Requirements

Most CMOS ADCs found in microcontrollers and ASICs have a sampled data comparator input structure. When the ADC charges the sampling cap, it requires instantaneous charge from the output of the analog source such as the LMT87 temperature sensor and many op amps. This requirement is easily accommodated by the addition of a capacitor (C\text{FILTER}).

#### 9.2.1.2 Detailed Design Procedure

The size of C\text{FILTER} depends on the size of the sampling capacitor and the sampling frequency. Because not all ADCs have identical input stages, the charge requirements will vary. This general ADC application is shown as an example only.

#### 9.2.1.3 Application Curve

![Figure 13. Suggested Connection to a Sampling Analog-to-Digital Converter Input Stage](image)

#### 9.2.1.4 Analog Output Transfer Function

![Figure 14. Analog Output Transfer Function](image)
Typical Applications (continued)

9.2.2 Conserving Power Dissipation With Shutdown

9.2.2.1 Design Requirements

Because the power consumption of the LMT87 is less than 9 µA, it can simply be powered directly from any logic gate output and therefore not require a specific shutdown pin. The device can even be powered directly from a microcontroller GPIO. In this way, it can easily be turned off for cases such as battery-powered systems where power savings are critical.

9.2.2.2 Detailed Design Procedure

Simply connect the V_DD pin of the LMT87 directly to the logic shutdown signal from a microcontroller.

9.2.2.3 Application Curves

![Figure 15. Simple Shutdown Connection of the LMT87](image)

10 Power Supply Recommendations

The low supply current and supply range (2.7 V to 5.5 V) of the LMT87 allow the device to easily be powered from many sources. Power supply bypassing is optional and is mainly dependent on the noise on the power supply used. In noisy systems it may be necessary to add bypass capacitors to lower the noise that is coupled to the output of the LMT87.
11 Layout

11.1 Layout Guidelines
The LMT87 is extremely simple to layout. If a power-supply bypass capacitor is used, it should be connected as shown in the Layout Example.

11.2 Layout Example

- VIA to ground plane
- VIA to power plane

![Figure 20. SC70 Package Recommended Layout](image)

![Figure 21. TO-92 LP Package Recommended Layout](image)

![Figure 22. TO-92 LPM Package Recommended Layout](image)
12 Device and Documentation Support

12.1 Receiving Notification of Documentation Updates
To receive notification of documentation updates, navigate to the device product folder on ti.com. In the upper right corner, click on Alert me to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

12.2 Community Resources
The following links connect to TI community resources. Linked contents are provided “AS IS” by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI’s views; see TI’s Terms of Use.

**TI E2E™ Online Community** **TI's Engineer-to-Engineer (E2E) Community.** Created to foster collaboration among engineers. At e2e.ti.com, you can ask questions, share knowledge, explore ideas and help solve problems with fellow engineers.

**Design Support** **TI's Design Support** Quickly find helpful E2E forums along with design support tools and contact information for technical support.

12.3 Trademarks
E2E is a trademark of Texas Instruments. All other trademarks are the property of their respective owners.

12.4 Electrostatic Discharge Caution
These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

12.5 Glossary
**SLYZ022 — TI Glossary.**
This glossary lists and explains terms, acronyms, and definitions.

13 Mechanical, Packaging, and Orderable Information
The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.
# Packaging Information

<table>
<thead>
<tr>
<th>Orderable Device</th>
<th>Status</th>
<th>Package Type</th>
<th>Package Drawing</th>
<th>Pins</th>
<th>Package Qty</th>
<th>Eco Plan</th>
<th>Lead/Ball Finish</th>
<th>MSL Peak Temp</th>
<th>Op Temp (°C)</th>
<th>Device Marking</th>
<th>Samples</th>
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</thead>
<tbody>
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<td>ACTIVE</td>
<td>SC70</td>
<td>DCK</td>
<td>5</td>
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<td>CU SN</td>
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<td>-50 to 150</td>
<td>BUA</td>
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(1) The marketing status values are defined as follows:
- **ACTIVE:** Product device recommended for new designs.
- **LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
- **NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
- **PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.
- **OBSOLETE:** TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".
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(3) **MSL, Peak Temp.** - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF LMT87:

- Automotive: LMT87-Q1

NOTE: Qualified Version Definitions:

- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects
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<th>B0 (mm)</th>
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*All dimensions are nominal.*
### TAPE AND REEL BOX DIMENSIONS

![Package Illustration]

*All dimensions are nominal

<table>
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<th>Device</th>
<th>Package Type</th>
<th>Package Drawing</th>
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<td>250</td>
<td>210.0</td>
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<td>35.0</td>
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</table>
NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
D. Falls within JEDEC MO-203 variation AA.
NOTES:

A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
D. Publication IPC-7351 is recommended for alternate designs.
E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.
NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
EXAMPLE BOARD LAYOUT

LPG0003A

TO-92 - 5.05 mm max height

TRANSISTOR OUTLINE

LAND PATTERN EXAMPLE

NON-SOLDER MASK DEFINED

SCALE:20X
Images above are just a representation of the package family, actual package may vary. Refer to the product data sheet for package details.
NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Lead dimensions are not controlled within this area.
4. Reference JEDEC TO-226, variation AA.
5. Shipping method:
   a. Straight lead option available in bulk pack only.
   b. Formed lead option available in tape and reel or ammo pack.
   c. Specific products can be offered in limited combinations of shipping medium and lead options.
   d. Consult product folder for more information on available options.
LP0003A

TO-92 - 5.34 mm max height

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